WELLCOMP TECHNOLOGY CO., LTD

APPROVAL SHEET

Model Name	Metal Strip Current Sensing Resistor
Part Number	WMCSS Series
Customer Name	
Customer P/N	
Issued Date	

Customer		Maker		
Approved Checked		Inspector Checked Prepar		



元璽科技股份有限公司

WELLCOMP TECHNOLOGY CO., LTD.

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Metal Type Current Shunt Resistor

Document No: 20131104001 Issued Date: 2013/11/04

Version: A02

Features

- ◆Able to withstand high temperature and high current
- ◆Excellent long term stability
- igspace5W up to 129A at 0.3m Ω
- ◆Chip size: 2512, and 3920
- Lead free, RoHS compliant for global applications and halogen free

Application

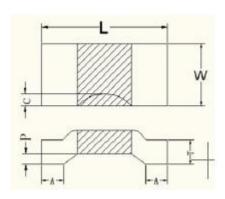
- ◆Power modules
- ◆Frequency converters
- ◆Current sensor for power hybrid sources
- ♦high current for automotive

Part Numbering System

<u>WMCSS 2512 R001 F H E A</u>

- (1) (2) (3) (4) (5) (6) (7)
- (1) Series Code
- (2) Size (EIA): Length x Width
- (3) Resistance: R001=1m Ω , 0R50=0.5m Ω
- (4) Tolerance: F=+/-1%, G=+/-2%, J=+/-5%
- (5) Power Rating: S=1/2W, C=1W, D=1.5W, E=2W,H=3W,I=5W
- (6) Packaging: T- Embossed paper tape, 7" reel E-Embossed plastic tape, 7" reel
- (7) Factory Code, A=Taiwan Factory

Dimension



Type	Resistance	Dimensions(mm)					
(inch size)	nesistance	L	W	Т	Α	C(Max.)	Р
WMCSS2512	$0.3m\Omega$	6.50±0.2	3.25±0.2	0.82±0.15	0.90±0.20	0.4	0.35±0.1
WMCSS2512	$0.5m\Omega$	6.50±0.2	3.25±0.2	0.72±0.15	0.90±0.20	0.4	0.35±0.1
WMCS2512	1m Ω	6.50±0.2	3.25±0.2	0.38±0.15	0.90±0.20	0.4	0.35±0.1
WMCSS3920	$0.3m\Omega$	10.2±0.2	5.20±0.2	1.42±0.15	1.80±0.30	0.6	0.50±0.1
WMCSS3920	$0.5m\Omega$	10.2±0.2	5.20±0.2	0.86±0.15	1.80±0.30	0.6	0.50±0.1
WMCSS3920	1m Ω	10.2±0.2	5.20±0.2	0.42±0.15	1.80±0.30	0.6	0.50±0.1



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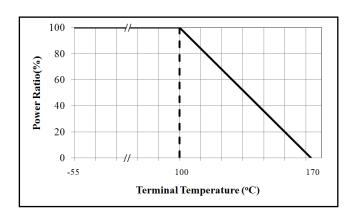
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Electrical Specification

Item	Power Rating	Resistance Range(m Ω)	Operation Temp. Range	TCR (PPM/°C)
	3W 5W	0.3		±150
WMCSS2512 WMCSS3920		0.5		±115
		1.0	FF~: 170°C	±100
		0.3	-55~+170°C	±150
		0.5		±70
		1.0		±50

Derating Curve



Performances

Environmental Performance

No.	Item	Test Condition	Specification
1	Short Time Overload	Loading 5 times rated power for 5 sec.	Δ R: ±(1%+0.0005Ω)
2	Temperature Coefficient of Resistance (T.C.R.)	+25°C/+125°C. (JIS-C5202-5.2) $TCR \text{ (ppm/°C)} = \frac{\Delta R}{R \times \Delta t} \times 10^{6}$	Refer to Electrical Specification
3	Moisture Resistance	The specimens shall be placed in a chamber and subjected to a relative humidity of 90~95% percent and a temperature of 25°C/65°C 10 cycles. (MIL-STD-202, Method 106)	Δ R: ±(1%+0.0005Ω)
4	High Temperature Exposure	The chip (mounted on board) is exposed in the heat chamber 125°C for 1000 hrs. (JIS-C5202-7.2)	Δ R: ±(1%+0.0005Ω)



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5	Load Life	Apply rated power for 1000 hours with 1.5 hours ON and 0.5 hour OFF. (JIS-C5202-7.10)	ΔR: ±(1%+0.0005Ω)
6	Rapid change of temperature	The chip (mounted on board) is exposed, -55±3°C (30min.)/+125±2°C (30min.) for 5 cycles. The following conditions as the following figure. (JIS-C5202-7.4) Ambient temperature 30 min. 30 min. 425(±2)°C 42	ΔR: ±(1%+0.0005Ω)

Function Performance

No.	Item	Test Condition	Specification
1	Bending Strength	Mount the chip to test 90mm(L)*40mm(W) FR4 printed circuit board substrate. Apply pressure in direction of arrow unit band width reaches 2mm(+0.2/-0mm) illustrated in the figure below and hold for 10±1 sec. (JIS-C5202-6.1) Unit: mm Position before bend Testing printed circuit board	ΔR: ±(1%+0.0005Ω)
2	Solderability	The specimen chip shall be immersed into the flux specified in the solder bath $235\pm5^{\circ}\mathbb{C}$ for 2 ± 0.5 sec. It shall be immersed to a point 10mm from its root. (Sn96.5/Ag3.0/Cu0.5) (JIS-C5 202-6.11) Molten solder Specimen SMD h = 10 mm H = 10 mm min.	Solder shall be covered 95% or more of the electrode area.

Remark:

a. The terminal electron temperature of component should below 100 $^{\circ}\! C$.



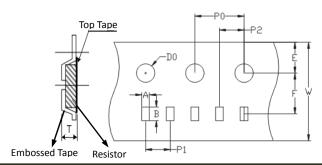
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Tape Packaging Specifications

◆Embossed Plastic Tape Specifications



Unit:mm

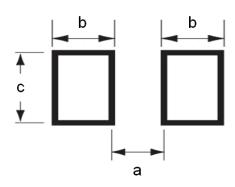
Type	Carrier Dimensions									
Type	Α	В	E	F	W	P0	P1	P2	D0	Т
2512	3.55±0.1	6.75±0.1	1.75±0.1	5.5 <u>±</u> 0.05	12.0±0.2	4.0 <u>±</u> 0.05	4.0±0.1	2.0±0.05	1.5±0.1	1.2±0.2
3920	5.5±0.2	10.8±0.2	1.75±0.1	7.5±0.05	16.0±0.2	4.0±0.05	12.0±0.1	6.0±0.05	1.5±0.1	1.2±0.2

Packaging

Size EIA (EIAJ)	2512	3920
Standard Packing Quantity (pcs /reel)	4,000	3,000

Storage Conditions

Recommended Solder Pad Layout



Typo	Pad Layout Dimension (mm)				
Туре	а	b	С		
2512	3.80	1.80	3.40		
3920	5.60	2.70	6.20		



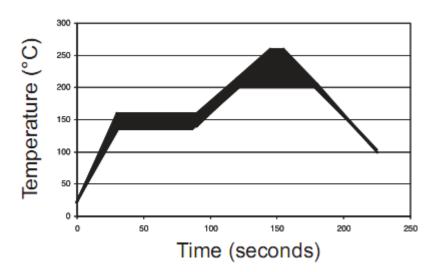
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Soldering Recommendations

- ◆ Peak reflow temperatures and durations:
 - IR Reflow Peak = 260° C max for 10 sec
 - Not suitable for wave soldering
- ◆ Recommended IR Reflow Profile:



ECN

Engineering Change Notice: The customer will be informed with ECN if there is significant modification on the characteristics and materials described in Approval Sheet.

单击下面可查看定价,库存,交付和生命周期等信息

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